題號: 190

國立臺灣大學 113 學年度碩士班招生考試試題

科目: 材料工程學

題號:190

節次: 6

共2頁之第1頁

※ 注意:請於試卷內之「非選擇題作答區」作答,並應註明作答之題號。

- 1. Please answer True or False for the following statements (30%)
 - (1) Grain refinement leads to high strength, high ductility and high toughness.
 - (2) Stored strain energy is the driving force for both recovery and recrystallization.
 - (3) Annealing twin usually forms during recrystallization.
 - (4) Grain growth undergoes at the expense of total grain boundary energy.
 - (5) In ceramics, yield strength is more important than fracture strength.
 - (6)「小龍女於寒玉床上修練內功」 should be considered as creep for the ice bed.
 - (7) In general, face-centered cbic crystalline materials have no ductile-to-brittle transition.
 - (8) In binary solid state, the Gibbs degree of freedom of eutectoid point is zero, but that of eutectic point is one.
 - (9) In the process of solidification, overcooling, in fact, is the driving force for transformation.
 - (10) A higher temperature leads to higher electrical resistance for conductor and semi-conductor.
 - (11) Direct bandgap usually shows higher electron mobility for indirect bandgap.
 - (12) Crystallinity of linear polymer is usually better than branched chain polymer.
 - (13) Cross-linked polymer usually exhibits a lower melting temperature, compared to linear polymer.
 - (14) Under seven crystal family, there are thirteen types of Bravais lattice.
 - (15) Equilibrium vacancy concentration is thermodynamically reversible.
- 2. Please explain the following terminology (10%):
 - (1) Spillover effect;
 - (2) CoWoS;
- 3. Ti is hexagonal (hcp) crystal. HCP-Ti (matrix) transforms into TiH₂ hydride (precipitate), Ti atoms will reconstruct into face-centered cubic (fcc) crystal, named fcc-Ti. Figure 1 shows the interface between fcc-Ti and hcc-Ti. The Orientation relationship between FCC-Ti and HCP-Ti: $\{10\overline{1}0\}_{hcp}||\{110\}_{fcc}|$ and $\langle1\overline{2}10\rangle_{hcp}||\langle1\overline{1}0\rangle_{fcc}$. Please calculate the lattice mismatch and define what type interface it is. Lattice constants: hcp-Ti: a = 0.2924 nm, c = 0.4625 nm; fcc-Ti: a=0.4080 nm. (10%)

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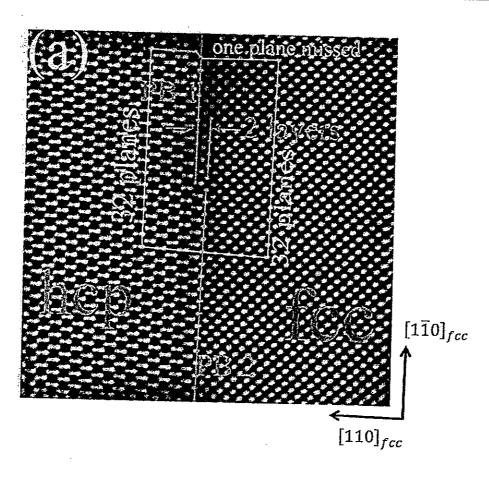


Figure 1 The interface between FCC-Ti and HCP-Ti.

- 4. Draw T and O interstitial sites for (1) face-centered cubic and (2) body-centered cubic crystal. (10%)
- 5. Draw the repeat units for the following polymers: (1) PVC; (2) PDMS; (3) PES. (10%)
- 6. What is the difference between the thermal conductivity of graphite and Al₂O₃? Which one is higher and why? (10%)
- 7. A silicon film is uniformly doped with 1018 cm⁻³ phosphorous atoms. What are electron and hole concentrations at 300 K. The intrinsic carrier concentration in silicon at 300 K is 1.0 x 10¹⁰ cm⁻³. (5%)
- 8. Write an essay in 120 words in English to summarize the importance of materials science & engineering in the Net-Zero era. (15%)